

**LTM2894-BGA-24LD-PBF 22mmx6.25mmX2.06mm (TABLE OF MATERIAL DECLARATION)**

*This product is RoHS compliant per EU RoHS Directive 2003/95/EC.*

**It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)**

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	HL832NX_A, AUS308	0.1540	Cured thermosetting resin (including inorganic filler)	Trade secret	0.03080	20.00
				Continuous Filament Fiber Glass	65997-17-3	0.02310	15.00
				Copper	7440-50-8	0.07491	48.64
				Modified Epoxy Acrylate Resin	186511-06-8	0.00873	5.67
				C.I pigment blue 15	147-14-8	0.00009	0.06
				Silicon dioxide	7631-86-9	0.00453	2.94
				Barium Sulfate	7727-43-7	0.00003	0.02
				3-methoxy-3-methylbutylacetate	103429-90-9	0.00143	0.93
				Organic yellow pigment	Trade secret	0.00009	0.06
				Dipropylene glycol monomethyl ether	34590-94-8	0.00079	0.51
				Heavy Aromatic Solvent naphtha	64742-94-5	0.00263	1.71
				Talc	14807-96-6	0.00376	2.44
				Gold	7440-57-5	0.00022	0.14
				Palladium	7440-05-3	0.00022	0.14
2	Solder Ball	SAC305	0.0211	Nickel	7440-02-0	0.00268	1.74
				Tin	7440-31-5	0.02037	96.50
				Silver	7440-22-4	0.00063	3.00
3	Die 1	U1	0.0004	Copper	7440-50-8	0.00011	0.50
				Silicon	7440-21-3	0.00043	100.00
				Silicon	7440-21-3	0.00078	100.00
4	Die 2	U2	0.0008	Silicon	7440-21-3	0.00078	100.00
				Silicon	7440-21-3	0.00078	100.00
5	Die 3	U3	0.0008	Silicon	7440-21-3	0.00043	100.00
				Silicon	7440-21-3	0.00043	100.00
6	Die 4	U4	0.0004	Component	-	0.05970	100.00
7	Bonding wire	Gold wire	0.0004	Gold	7440-57-5	0.00041	100.00
9	Solder paste	95Sn5Sb	0.0085	Silver	7440-31-5	0.00804	95.00
				Dicyandiamide	7440-36-0	0.00042	5.00
10	Encapsulation	EpoxyResin	0.2596	Solid Epoxy Resin	Trade secret	0.00779	3.00
				Phenol Resin	Trade secret	0.00779	3.00
				Fused Silica	60676-86-0	0.23490	90.50
				Carbon Black	1333-86-4	0.00130	0.50
				Metal Hydroxide	Trade secret	0.00779	3.00
11	Die attach	Epoxy	0.0005	Silver	7440-22-4	0.23035	88.75
				Epoxy Resin A	9003-36-5	0.00779	3.00
				Epoxy Resin B	Trade secret	0.00779	3.00
				Diluent	Trade secret	0.00779	3.00
				Coupling agent	Trade secret	0.00519	2.00
				Dicyandiamide	461-58-5	0.00065	0.25
Total Package Weight			0.5061				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts